

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT(S):	Okada	CONF. NO.:	4969
SERIAL NO.:	10/581,657	GROUP NO.:	2822
FILING DATE:	June 7, 2007	EXAMINER:	Potter, R.K.
TITLE:	SYSTEM AND METHOD TO REDUCE METAL SERIES RESISTANCE OF BUMPED CHIP		

Mail Stop Amendment  
Commissioner for Patents  
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**AMENDMENT AND RESPONSE**

This paper responds to the Office Action mailed on January 11, 2008, in the above-identified patent application.

Please amend the above-identified patent application as follows, without prejudice:

- **Listing of claims** begins on page 2 of this paper; and
- **Remarks** begin on page 6 of this paper.